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(54) **Title:** METHOD FOR ATTACHING AND DETACHING WAFERS DURING INTEGRATED CIRCUIT MANUFACTURING

(57) **Abstract:** A method for attaching and detaching wafers during integrated circuit manufacturing is disclosed. Initially, a reusable carrier is formed by depositing a layer of partially transparent light-absorbing material (LAM) on a transparent carrier. An ultraviolet (UV) curable adhesive is deposited on a wafer. The wafer is then placed on the reusable carrier with the partially transparent LAM layer in contact with the UV-curable adhesive to form a carrier stack. Next, an UV light is directed through the transparent carrier and the partially transparent LAM layer in order to cure the UV-curable adhesive. After the wafer has been processed, a light pulse is sent from a flashlamp through the transparent carrier in order to detach the wafer from the transparent carrier.

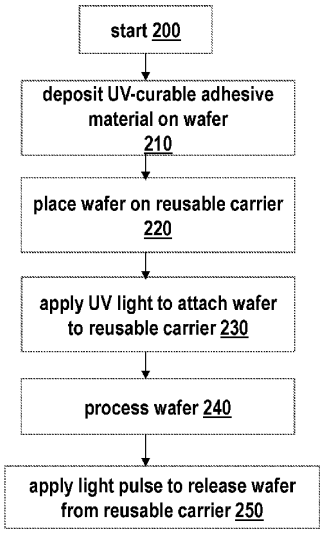


Figure 2

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